Mounting Accessories for Board

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Mounting Accessories for Heatsinks HS1, HS2 & HS3

M1, M2, M3 are NOT needed when TO-220-Flatspack package is used.

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Notes

ZZ1

These assemblies are ESD sensitive. ESD precautions shall be observed.

ZZ2

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

ZZ3

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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